



RE230-LF

- Epoxy fibre-glass FR4 1.60 mm
- Single-sided 35 µm Cu
- Hot air leveling (HAL-leadfree)
- Surface with soldering stop mask
- Hole spacing 2.54 x 2.54 mm
- 40 x 58 soldering pads 2.00 x 2.00 mm
- Hole diameter 1.02 mm (0.40")
- 2 potential strips
- Max. working temperature 150 °C (302 °F)
- Size 114.30 x 165.10 mm (4.5" x 6.5")